

ABSTRACT OF THE DISCLOSURE

A system, an automatic machine-implemented method, and a machine-readable medium recording a set of instructions to perform such method are provided for de-compacting a layout for a portion of an integrated circuit. According to the method, a spacing is enlarged between neighboring features of a path of a plurality of paths of the layout provided that the length of the path does not then exceed a predetermined dimensional constraint and connectivity is maintained between the neighboring features and any features of the layout to which they are connected. This process is repeated to enlarge at least one other spacing of the layout.

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